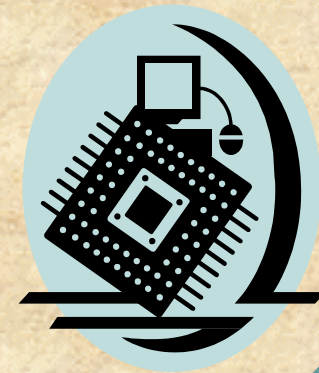


Digital Front-End Electronics

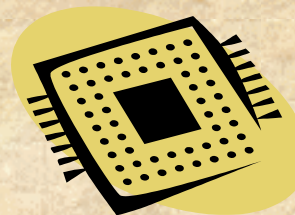
Preshower meeting.
CMS week 3-7 Dec. 2001

KLOUKINAS Kostas EP/CME-PS



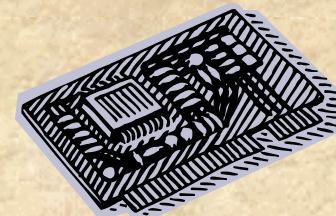
- **ASIC design activities**

- K-chip design
 - SRAM design and testing
 - Timing & Control logic design



- **System level design activities**

- Readout & Control system design
- Motherboard design

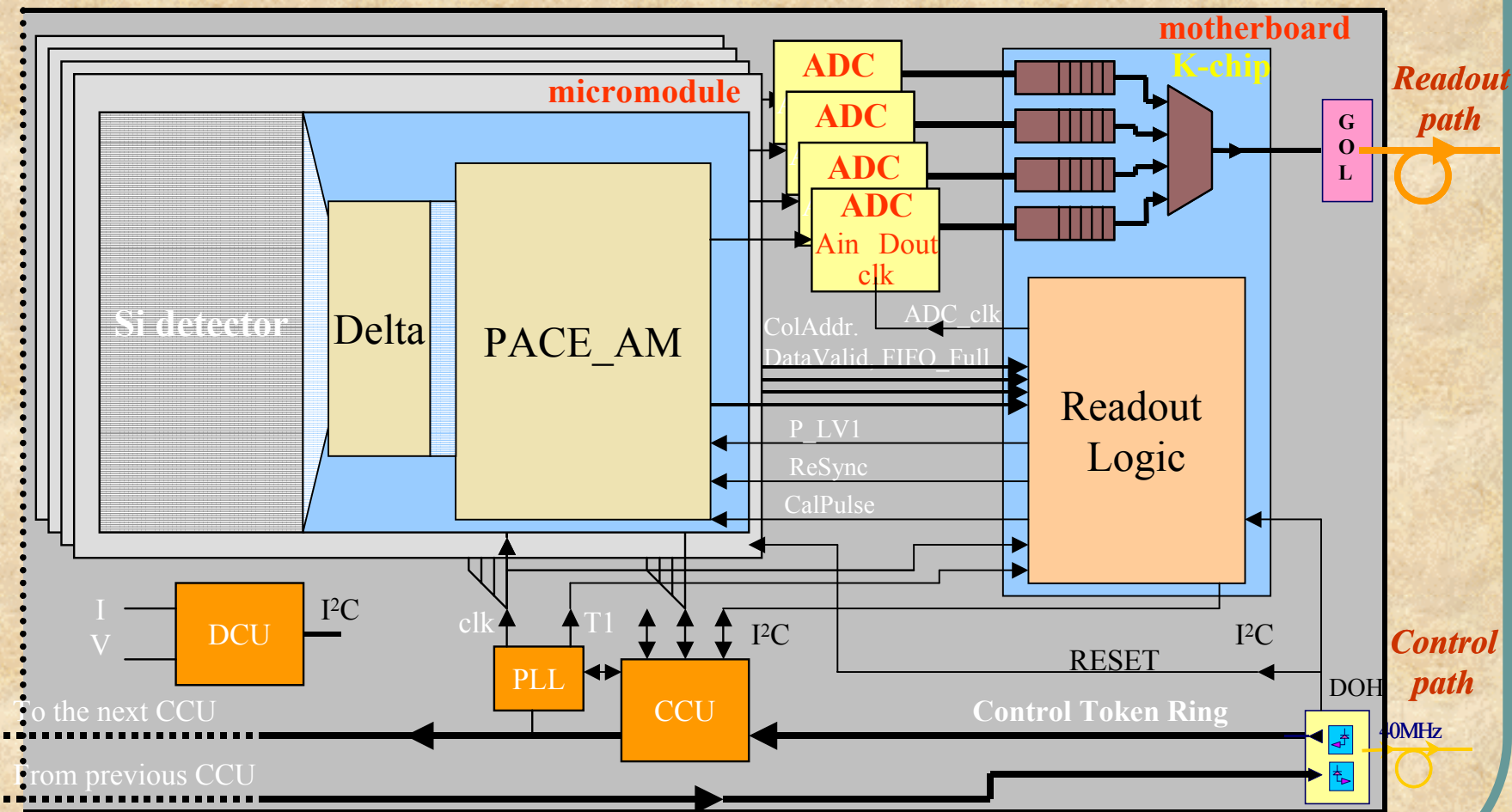


- K-chip motherboard design.

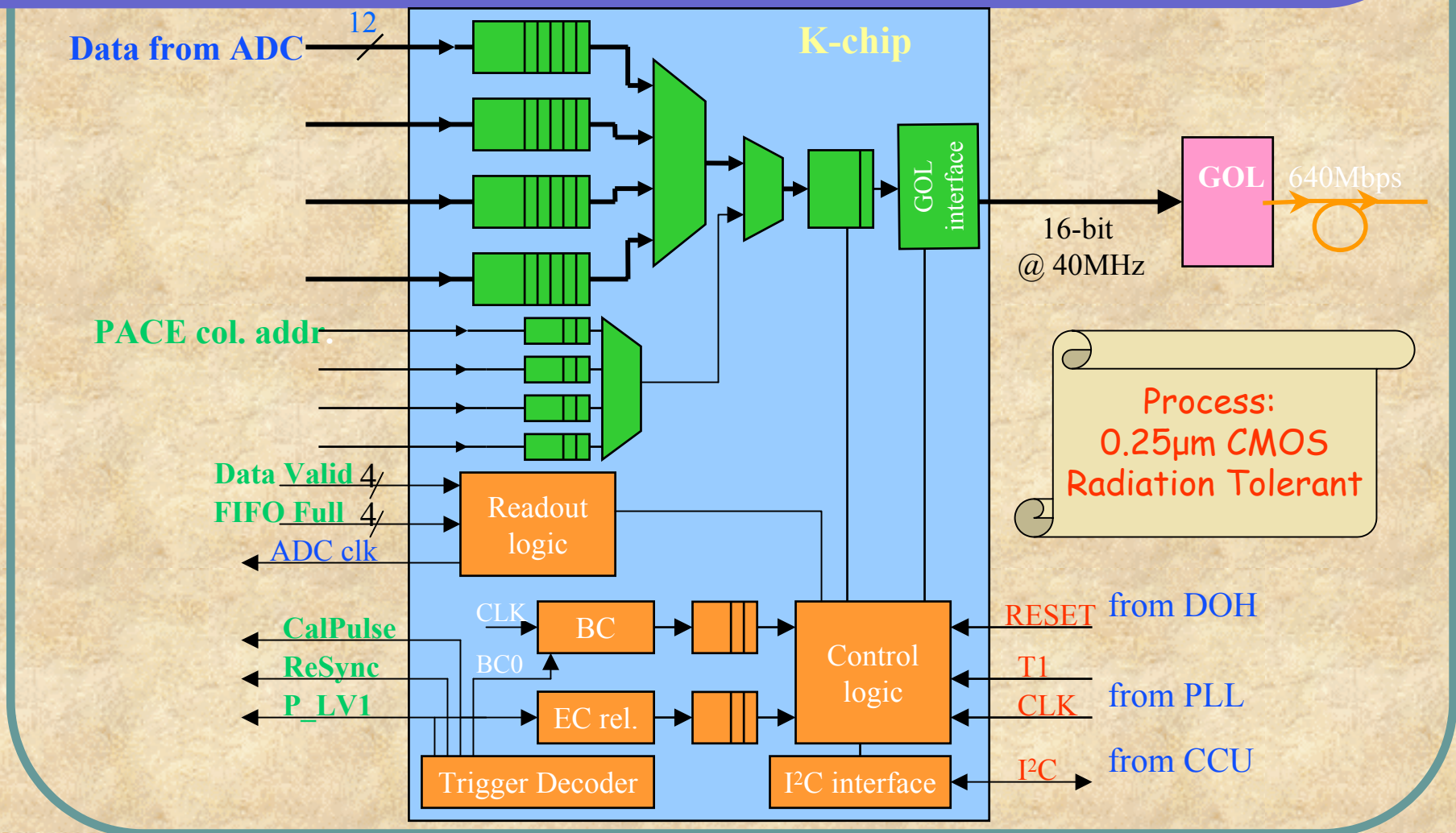
A reduced version of the system motherboard. It will serve as a test bench for evaluating the K-chip functionality. This version will not incorporate the slow control system and the high speed link chip (GOL).

- System motherboard design.

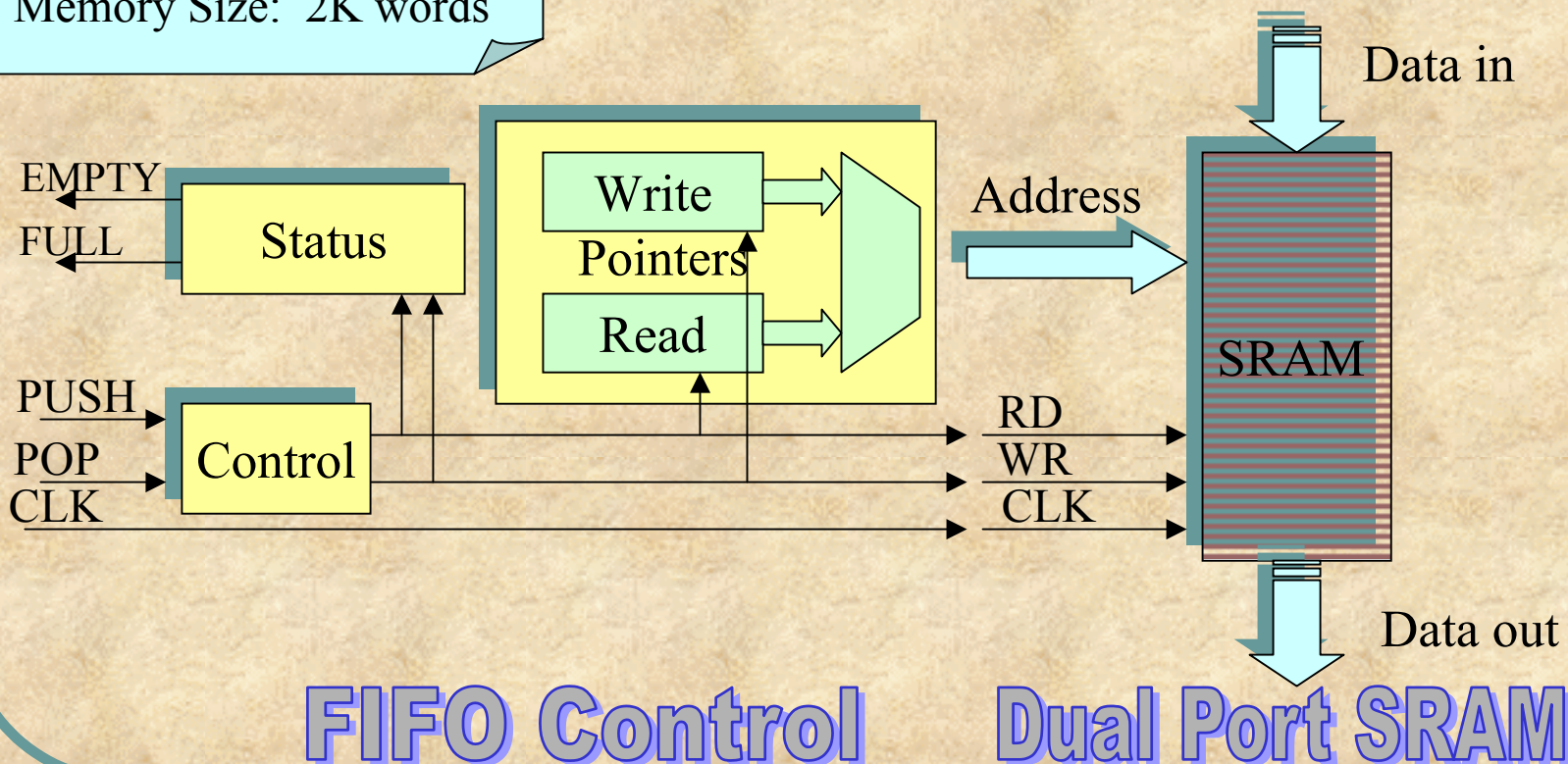
First version of the *final system* motherboard design. It will include the high speed link and the slow control system.



K-chip Block Diagram



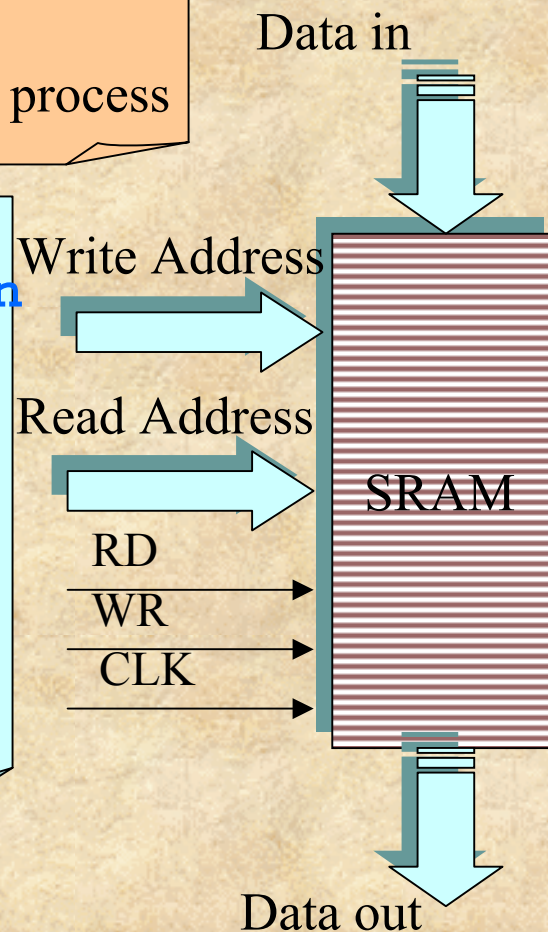
Synchronous FIFO
 Operation freq.: 40MHz
 Data bus width: 12 bits
 Memory Size: 2K words



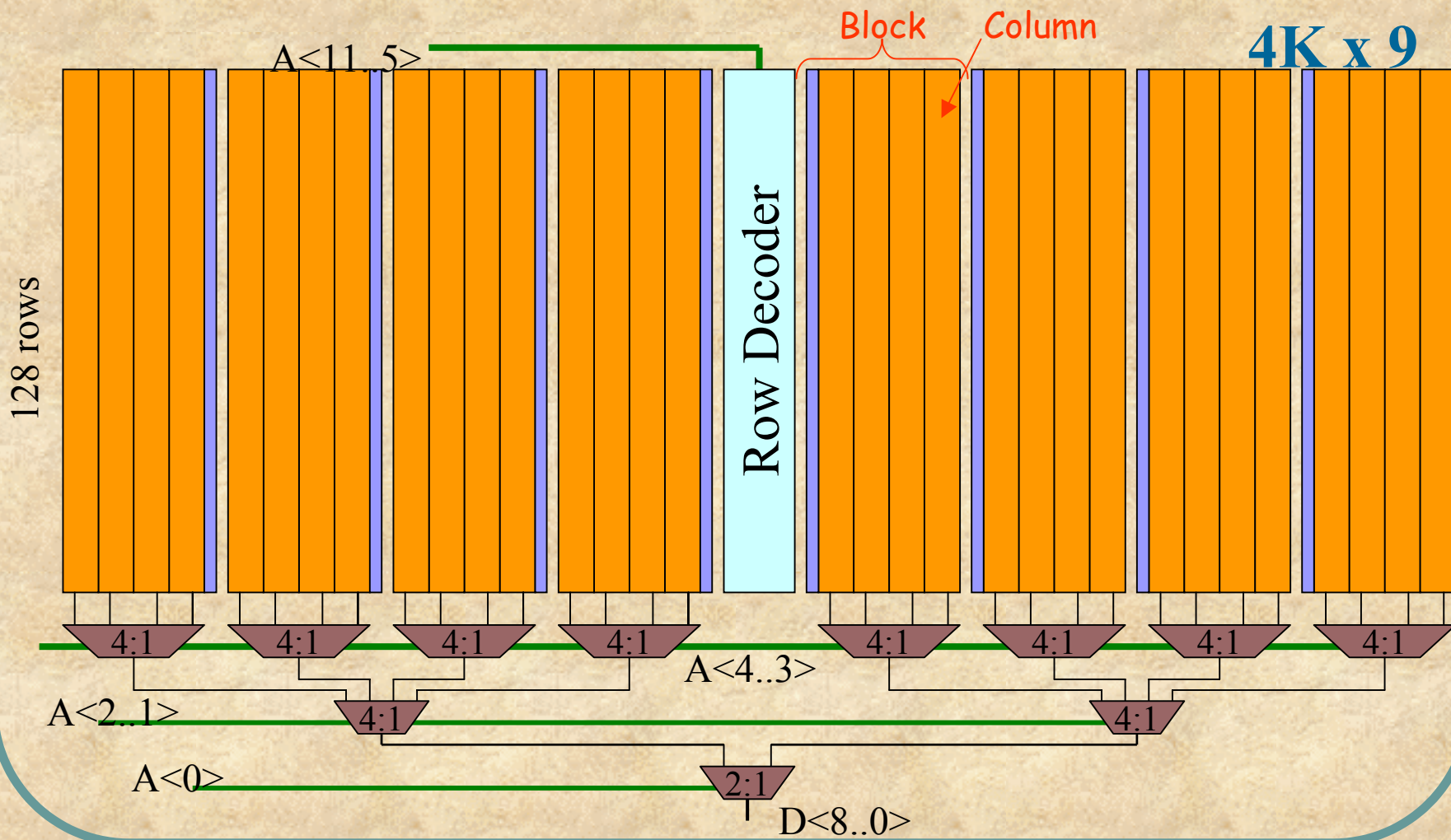
Radiation Tolerant 0.25 μ process

Design Specifications

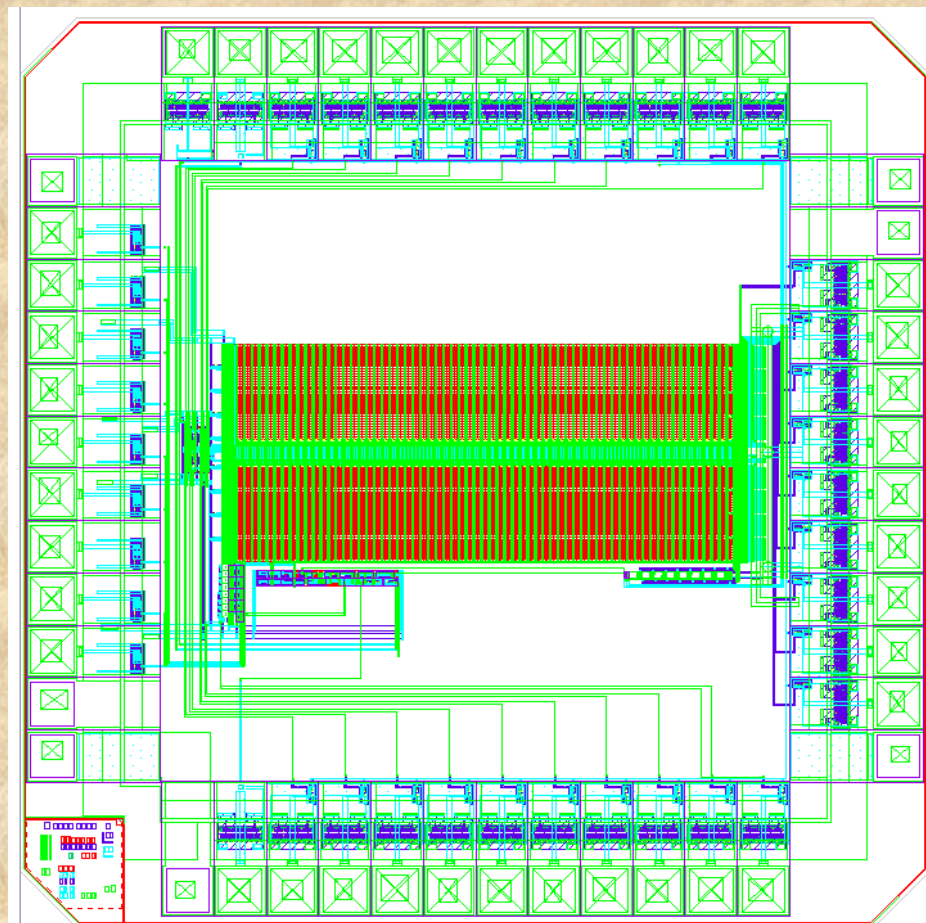
- Synchronous *pseudo* Dual Port Operation
- Operating frequency: 40 MHz
- Flexible configuration of memory size !
- Radiation Tolerant Design
- Data bus width: (n x 9)bits
- Data arrangement: 8 bit + 1 parity bit
- Memory Size: up to 4K words
- Registered Inputs, Latched outputs



Modular SRAM design.

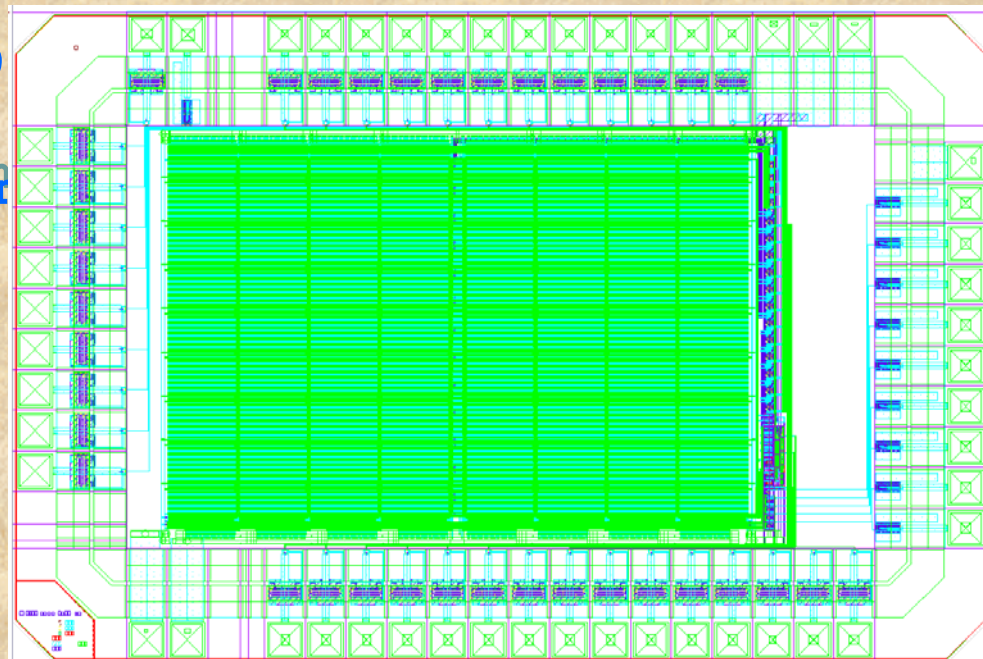


- 1st Prototype (CERN MPW 4)
- Configuration: 1Kx9 bit
- Size: $\sim 560\mu\text{m} \times 1,300\mu\text{m}$
- Area: $\sim 0.73\text{mm}^2$
- Submitted: Oct. 2000.
- Chip Received: Feb 2001
- Tested: Apr. 2001
- Status: O.K.



Design: CERN_SRAM_1K
 Designer: Kloukinas Kostas
 EP/CME-PS

- 2nd Prototype (CERN MPW 5)
- Configuration: 4Kx9 bit
- Size: $\sim 1,850\mu\text{m} \times 1,300\mu\text{m}$
- Area: $\sim 2.4\text{mm}^2$
- Submitted: May 2001
- Chip Received: Aug. 2001
- Tested: Oct. 2001
- Status: O.K.



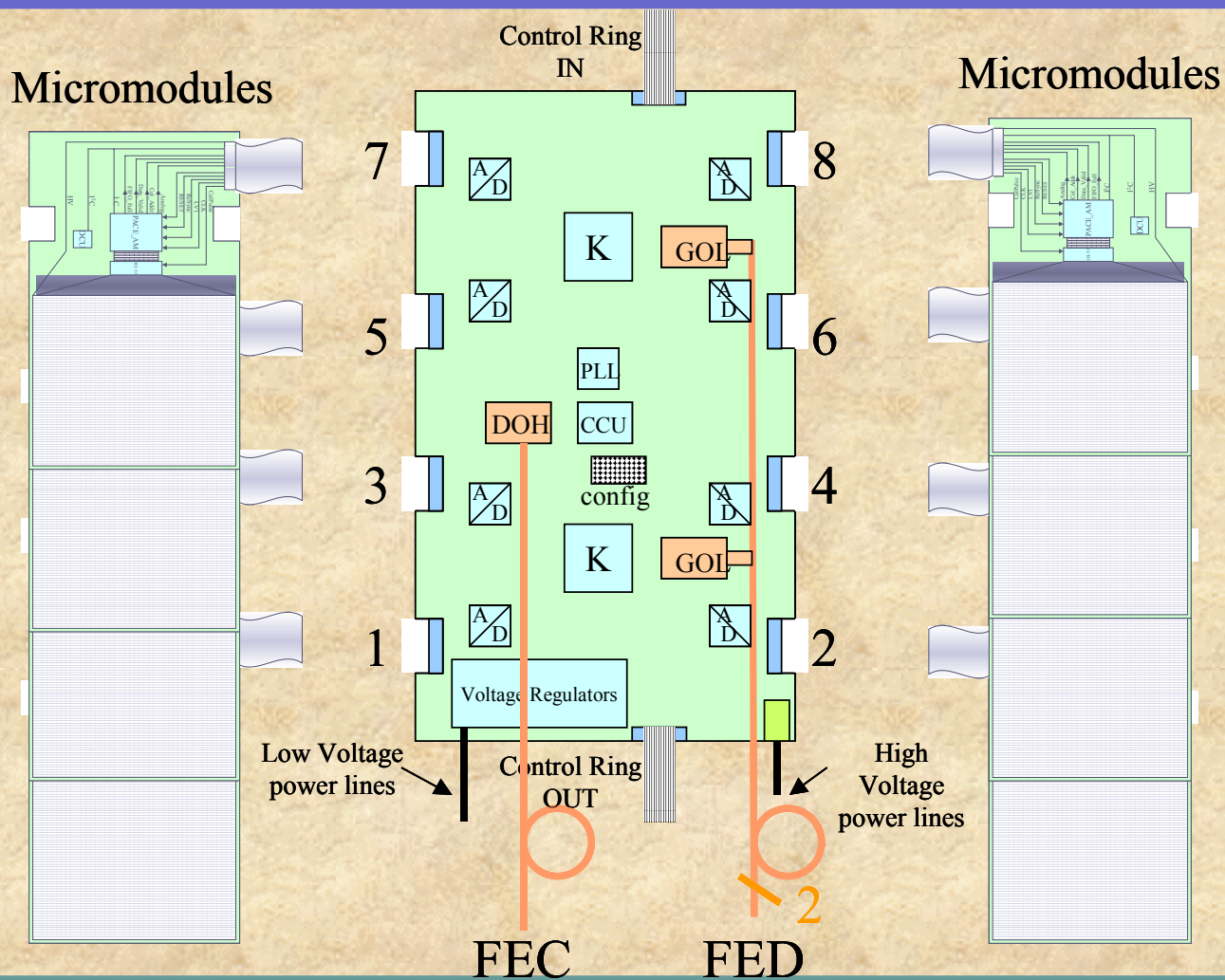
Design: CERN_SRAM_4K
 Designer: Kloukinas Kostas
 EP/CME-PS

● Functional tests (4Kx9bit SRAM)

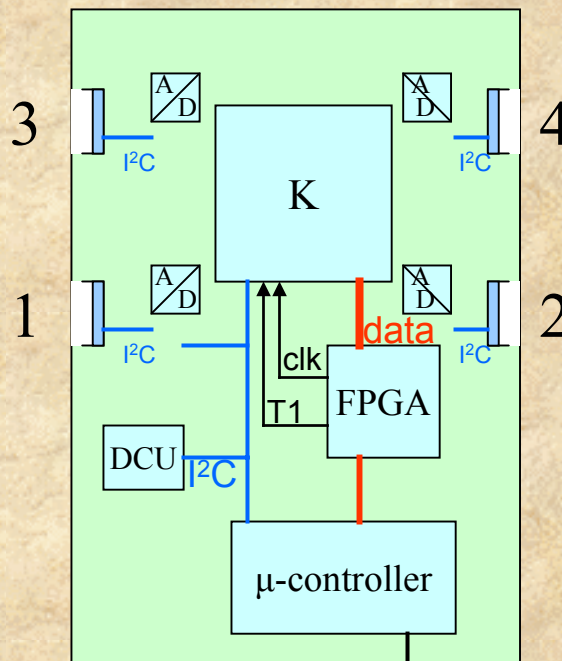
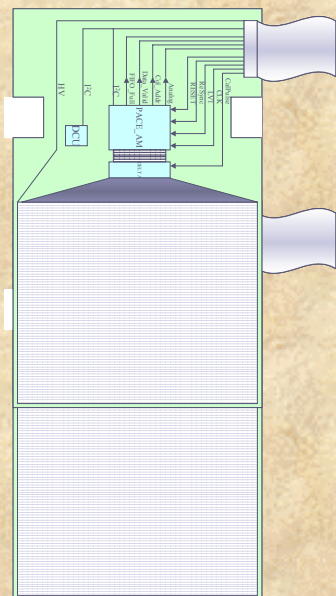
- Max operating frequency: 60MHz @ 2.5V
- Read access time: 7.6ns @ 2.5V
- Power dissipation: 15 μ W / MHz @ 2.5V for simultaneous R/W access cycles (0.60mW @ 40MHz).
- Design tested for process variations: -3σ , -1.5σ , typ, $+1.5\sigma$, $+3\sigma$

● Irradiation tests

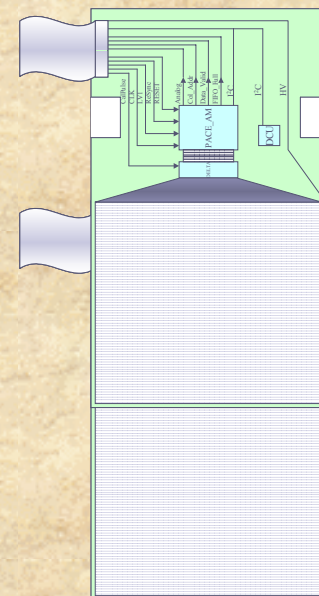
- Total ionizing dose: up to 10MRad
 - No increase in power dissipation.
 - No degradation in performance.
- Single Event Upsets: under preparation (in collaboration with EP/MIC group)



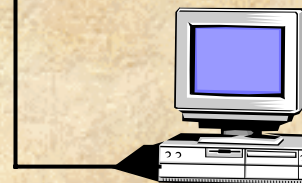
Micromodules



Micromodules



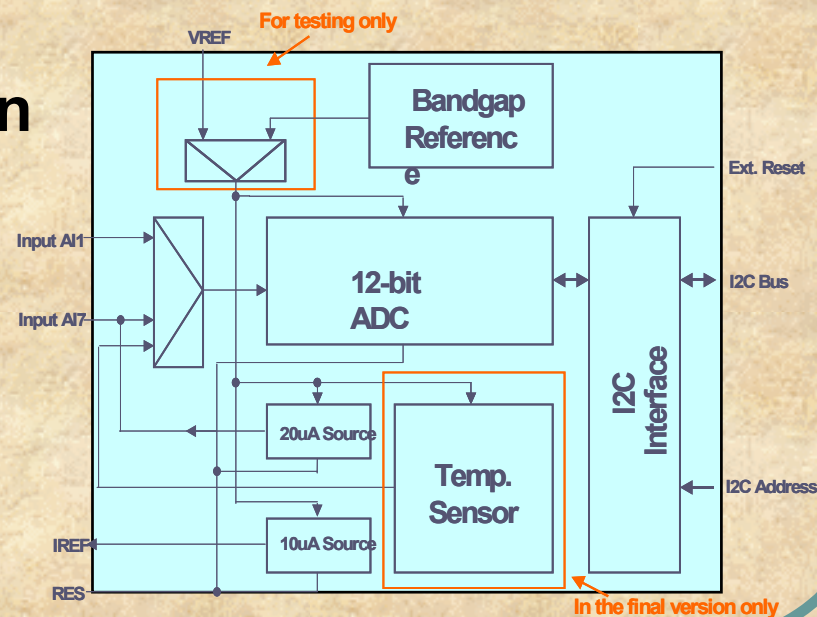
- FPGA
 - Generates Clock & Trigger Commands.
 - Data FIFO, emulating optical link.
- μ -controller
 - I²C master device.
 - Data readout controller.



- K-chip motherboard
 - Test the functionality of the K-chip.
 - Verify the readout system operation.
 - Proper distribution of the fast timing signals (clk, Trigger commands) on the motherboard and the μ -module.
 - Test the compatibility of the I2C interfaces of the FE chips (PACE, K-chip, DCU).
 - Test the interfacing between ASICS powered from different supply voltages.
 - PACE & ADC @ 5V, K-chip & DCU @ 2.5V.
 - Evaluate the operation of the DCU chip.

- **Detector Control Unit** (CMS Tracker control system)
 - 12-bit ADC, 1ms conversion time
 - 6 analog inputs
 - on-chip temperature sensor (resolution: 0.5°C)
 - I²C interface

- **Investigate possible use in the Preshower Front-End system**
 - Temperature measurement
 - PACE DACs calibration
 - Leakage current measurements





Summary & Future Plans



- **K-chip design**
 - Data FIFO designed & tested
 - Work in progress on:
 - Digital control logic (PACE readout logic, trigger control, I²C, etc)
 - 5Volt tolerant pads
 - Differential driver pads for the ADC clock
 - Target submission: CERN MPW 7 (Feb. 2002)
- **Motherboard design**
 - K-chip motherboard design has started
 - Include as much functionality of the final system as possible.
 - Board expected to be ready in May 2001